



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSZ099N06LS5	Issued	14. February 2022
MA#	MA005624888		
Package	PG-TSDSON-8-35	Weight*	34.44 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.281	0.82	0.82	8167	8167
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		106	
	non noble metal	zinc	7440-66-6	0.015	0.04		426	
	non noble metal	iron	7439-89-6	0.293	0.85		8512	
	non noble metal	copper	7440-50-8	11.903	34.56	35.46	345642	354686
wire	noble metal	gold	7440-57-5	0.028	0.08	0.08	818	818
encapsulation	organic material	carbon black	1333-86-4	0.036	0.10		1041	
	plastics	epoxy resin	-	1.649	4.79		47878	
	inorganic material	silicondioxide	60676-86-0	16.237	47.16	52.05	471494	520413
leadfinish	non noble metal	tin	7440-31-5	0.420	1.22	1.22	12209	12209
plating	noble metal	silver	7440-22-4	0.003	0.01	0.01	91	91
solder	noble metal	silver	7440-22-4	0.011	0.03		333	
	non noble metal	tin	7440-31-5	0.023	0.07		666	
	non noble metal	lead	7439-92-1	0.424	1.23	1.33	12317	13316
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			27	
	non noble metal	zinc	7440-66-6	0.004	0.01		108	
	non noble metal	iron	7439-89-6	0.075	0.22		2167	
	non noble metal	copper	7440-50-8	3.030	8.80	9.03	87998	90300
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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